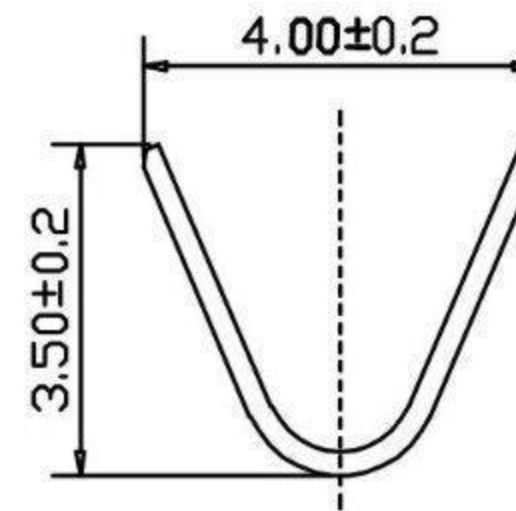
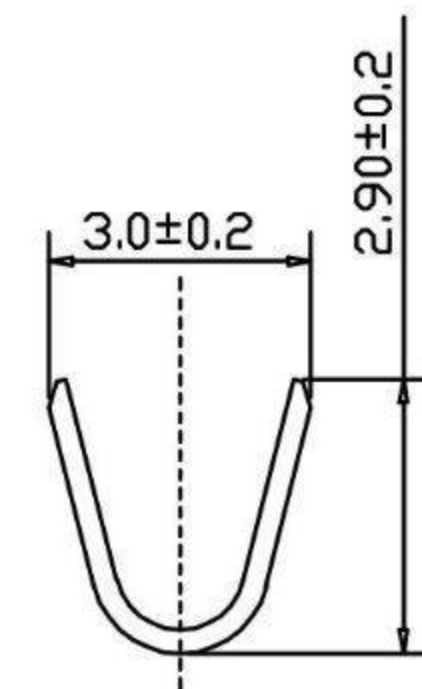


NOTES:

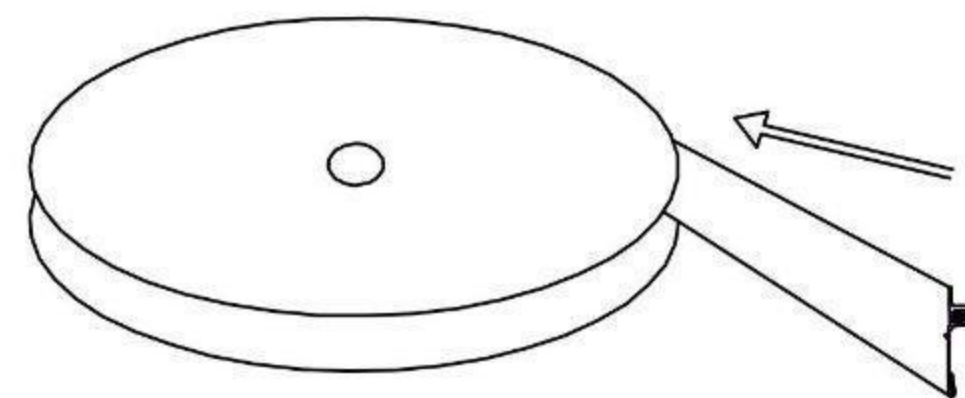
- 1.MATERIALS: PHOSPHOR BRONZE(C5191-H)
- 2.BURR: 0.05MAX;WARPAGE: 0.10MAX
- 3.Wire Range: AWG#18~#22 2.10mm(MAX)OD
- 4.PLATING:
 - (1) BECHICS CLASH AFTER PLATING: 20u'MIN Ni;80u'MIN TIN;CONTACT AREA GOLD: 0.5u'
 - REEK SALT TEST 12H MIN
 - (2) BECHICS CLASH AFTER PLATING: 20u'MIN Ni;80u'MIN TIN;CONTACT AREA GOLD: 3u'
 - REEK SALT TEST 12H MIN
- 5.LOOSE CONTACT: RETENTION FORCE: 2.5kg MIN
- 6.REQUIRE : cd≤5ppm pb≤50ppm
hg≤nd cr≤nd



SECTION: (A-A)



SECTION: (B-B)



电镀后的收料方向

RoHS Compliant		HSM 玄茂科技股份有限公司		HSUAN MAO TECHNOLOGY CO., LTD.	
APPD. 核准: BETTY	SCALE 比例: 参考	TOLERANCE		PART NAME 品名	
DWG. 製圖: KAREN		DIM	TOL	DIM	TOL
DATE 制表日: 2014/09/10	UNIT 單位: MM	X	/	X"	/
	PAGE 張數: 1 OF 1	XXX	±0.15	XXX"	±0.2"
		XXXX	±0.05	XXXX"	±0.1"
		SIZE 紙張尺寸: A4	PART NO. 料號: T1270-SPDL0000R		
		REV. 版本: B	1.27mm SATA TERMINAL LOW TYPE SELECTIVE GOLD PLATING MATERIAL:PHOSPHOR BRONZE SUITABLE FOR 18~22AWG ROHS		